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## ISO-DYNAMIQUE MICROSYSTEMS

### DAGE 4300 BONDTESTER

The DAGE 4300 is a new generation bondtester which complements DAGE's proven semi-automatic wafer testers (DAGE 4000W). It has been engineered in accordance with the strict standards of semiconductor foundries and subcontractors to meet the growing demand for handling and bump shear testing on 300mm wafers. It offers similar advantages to the DAGE 4000W in the avoidance of manual handling of valuable wafers and increased productivity in bump testing.



### Key Features

- Joystick manipulation of the test head over 100% of wafer surface without repositioning the wafer on the chuck.
- Semi-automatic test routines for bondtesting of the entire wafer surface without repositioning the wafer on the chuck (no camera system needed). 2 reference points needed per wafer.
- 460mm x 300mm XY stage
- Wafer size 200mm or 300mm
- Optional image capture system
- 360 degree manual chuck rotation
- 360 degree loadtool rotation. Automatic during auto test; manual under joystick control.
- Safety interlocks on wafer chuck
- Frame protection for 300mm wafer
- Provision for interface to customer's robot handler and other SMIF equipment

For additional information, please contact:  
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